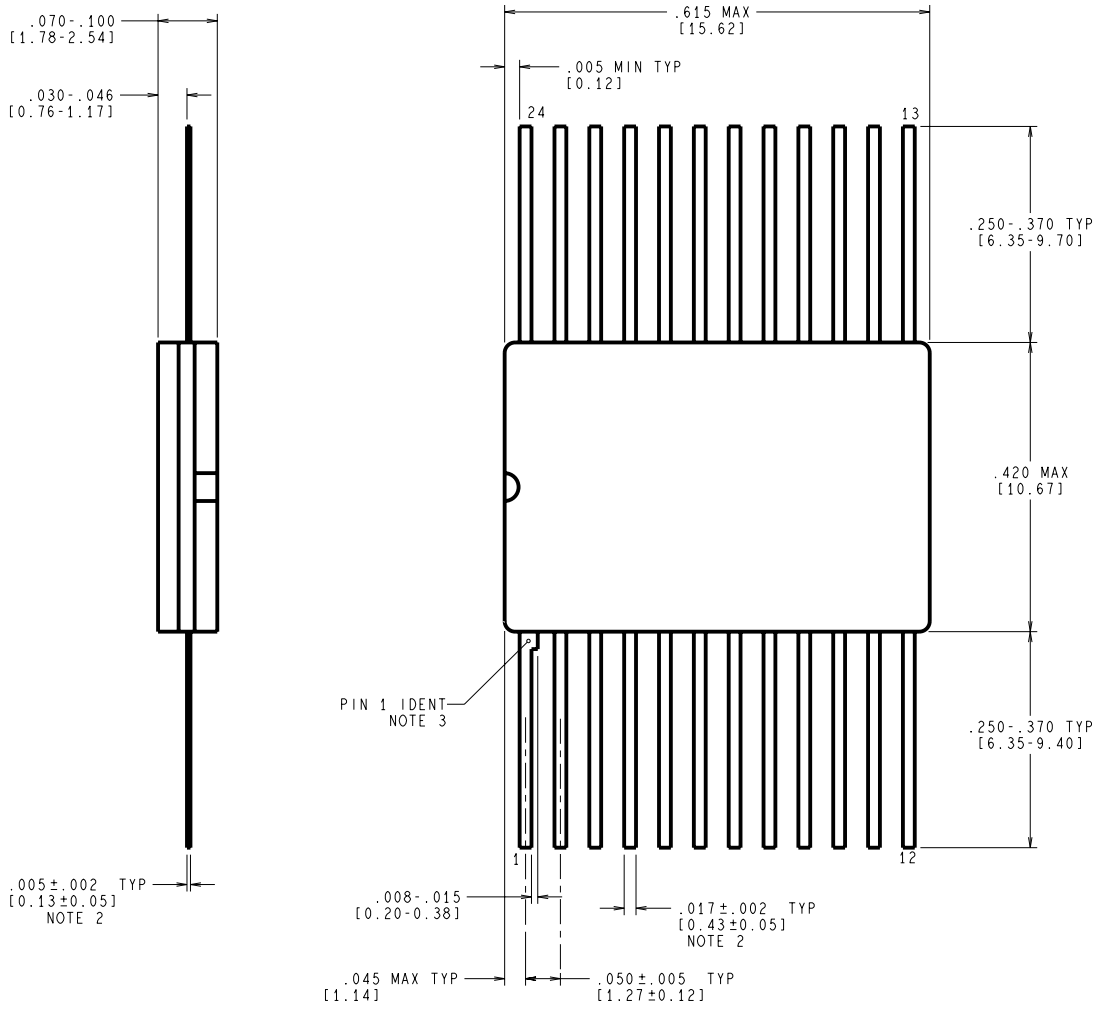
REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
F	REVISE AND REDRAW PER CURRENT STANDARD; UPDATE TITLE & MIL/AERO STAMP.	11046	07/13/95	MS/



CONTROLLING DIMENSION IS INCH
VALUES IN [ ] ARE MILLIMETERS

NOTES: UNLESS OTHERWISE SPECIFIED

1. LEAD FINISH: SOLDER DIPPED WITH Sn60 OR Sn63
   SOLDER CONFORMING TO A MINIMUM THICKNESS
   OF 200 MICROINCHES/ 5.08 MICROMETERS.
   SOLDER MAY BE APPLIED OVER LEAD BASIS METAL OR Sn PLATE.
2. LEAD THICKNESS MAY BE INCREASED BY .003 INCHES/ 0.08 MILLIMETERS
   MAXIMUM AFTER LEAD FINISH APPLIED.
3. LEAD 1 IDENTIFICATION SHALL BE:
   a) A NOTCH OR OTHER MARK WITHIN THIS AREA
   b) A TAB ON LEAD 1, EITHER SIDE
4. NO JEDEC REGISTRATION AS OF 07/17/95.

MIL-PRF-38535
CONFIGURATION CONTROL

APPROVALS	DATE
DRAWN: MARTA SUCHY	07/13/95
DFTG. CHK.	
ENGR. CHK.	

PROJECTION INCH [MM]

National Semiconductor
2900 Semiconductor dr, Santa Clara, CA 95052-8090

CERPAC, 24 LEAD

SCALE	SIZE	DRAWING NUMBER	REV
N/A	C	MKT-W24C	F

DO NOT SCALE DRAWING | SHEET 1 of 1